

Title (en)  
HOT STAMPING MACHINE

Title (de)  
HEISSPRÄGEVORRICHTUNG

Title (fr)  
DISPOSITIF D'ESTAMPAGE À CHAUD

Publication  
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Application  
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Abstract (en)  
[origin: WO2014064114A1] The invention relates to a hot stamping machine (1), comprising a stamping device (2) for transferring a transfer layer (15u) arranged on a carrier layer (15t) of a hot stamping foil (15) onto a substrate (14). The hot stamping machine comprises a heatable stamping roller (11) and a counter-pressure roller (12) between which a stamping gap (16) is defined, and a downstream releasing device (3) for releasing the carrier layer (15t) from the transfer layer (15u) transferred onto the substrate (14). Between the stamping gap (16) and the releasing device (3) a flat contact element (18) is arranged below the stamped substrate (17), which contact element is directly contiguous to the stamping gap (16) or is spaced apart from the stamping gap (16) by < 1mm or is arranged to overlap the stamping gap (16).

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